

PRODUCT NUMBER
75189-XXX-XXLF

RoHS COMPLIANT & COMPATIBLE, SEE NOTE 7

NUMBER OF CONTACTS, 2 TO 18.

PIN STYLE

PLATING:

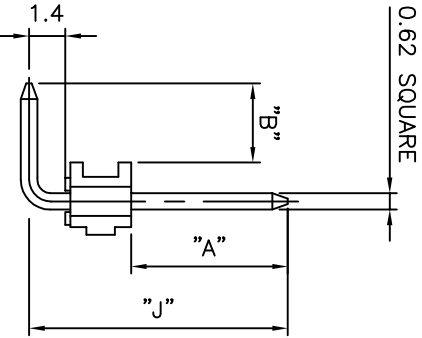
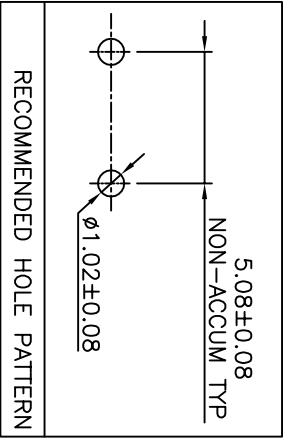
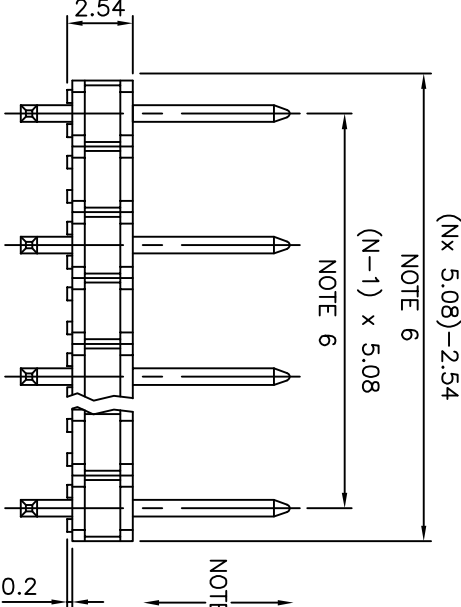
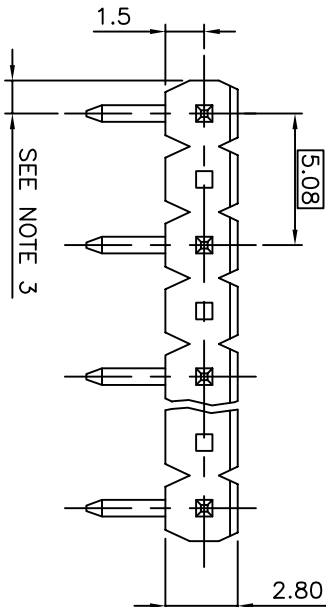
1 = 0.76µm FULL GOLD

1.27µm Ni MIN UNDERPLATING

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC FLAME RETARDANT PER UL94-V0, COLOR BLACK.
2. PIN MATERIAL : PHOSPHOR BRONZE.
3. DIM 1.27^{+0.03}_{-0.13} FOR MOULDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN, DIM 1.02 TO 1.7 MAX APPLIES.
4. PIN PUSH OUT FORCE : 12N MIN.
5. PRODUCT PACKAGED IN POLY BAGS.
6. TO DETERMINE DIMENSIONS :
N = NUMBER OF CONTACTS
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - LF MEANS THE PRODUCT IS LEAD-FREE
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - c - LABELING:
 - d - LEGAL STATEMENT: SEE GS-47-0004

STYLE	"A"±0.2	"B"±0.35	"J" REF
01	5.72	2.57	9.65
13	5.72	3.45	9.65



mat'l. code		surface		tolerance		projection		product family	
itr	ecn no	dr	date	ISO 1302	ISO 406	ISO 1101		title	BSTIK
H	F10076	JMC	91.02.25	tolerances unless otherwise specified				HEADER,SR,RA,	
J	F05-0186	JCO	05.06.09	angles	X ±0.3			POL 5.08mm	
K	F06-0196	LMU	06.06.20	linear	XX ±0.15				
L	B-19261	LMU	14.10.31	dr	LMU	05.06.09		dwg no	75189
				engr	J.COMPAIGNON	05.06.09		sheet 1 of 1	
				chr				size	A3
				appd	JCO	05.06.09		type	CUSTOMER
								Drawing	
sheet	revision								
index	sheet								